

IN THE SPECIFICATION

Please amend the abstract of the disclosure on page 63 as follows:

ABSTRACT

~~The object of the present invention is to provide a metal heater capable of quickly heating a semiconductor wafer and the like with slight unevenness of temperature at the time of heating, and causing no warping or sagging in the metal plate employed therein.~~

~~The metal heater of the present invention comprises a metal plate and a heating element, wherein the metal plate has a thickness of 50 mm or less and a surface flatness of 50 μm or less, and an outer rim of a region where the heating element is formed is at a position within 25% of the diameter of the metal plate from an outer circumference of the metal plate.~~

A metal heater including a metal plate having a heating face, a supporting device for supporting a semiconductor wafer over and apart from the heating face, and a heating element positioned to heat the metal plate. The metal plate has a thickness of 50 mm or less, the heating face has a surface flatness of 50 μm or less, and the heating element extends to an area within 25% of a diameter of the metal plate from an outer circumference of the metal plate.